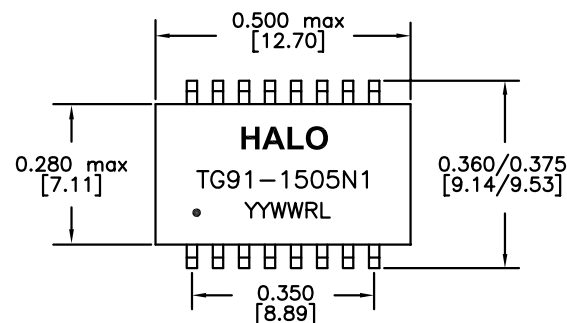
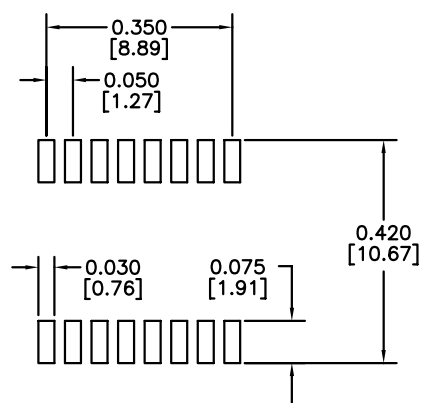


DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



RECOMMENDED SOLDER PAD DIMENSIONS

PART NO. : TG91-1505N1RL

16PIN DUAL SMT T1/E1 ISOLATION MODULE
RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO

P1-3:P16-14

P6-8:P11-9

1CT:2.4CT±2%

1CT:1CT±2%

OCL P1-3,P6-8

1.5mH typ

DCR P1-3,P6-8

0.8Ω max

Cw/w

35pF max

LL P1-3,P6-8

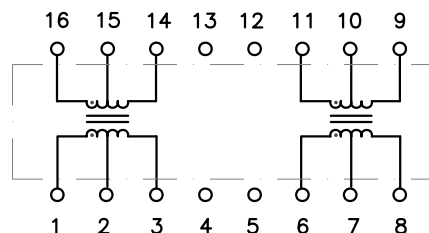
0.5μH max

CROSSTALK 0.5-5MHz

-60dB typ

ISOLATION

1,500Vrms



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE SMT ISOLATION MODULE

FOR T1/E1 (1:2.4, 1:1)

PART NO. TG91-1505N1RL

SCALE NONE

PAGE 1 OF 1

SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE 1505N1RL.DWG

DATE

4/19/05

2/3/10

2/3/10

REV.

A

B

C

DESC.

FIRST ISSUE

UPDATE

PROD. RELEASE

DATE

4/19/05

9/2/07

2/3/10

